

## Announcement

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### INTERNATIONAL SOCIETY FOR HYBRID MICROELECTRONICS

The International Society for Hybrid Micro-electronics is based in the U.S.A., and there are independent parallel organisations throughout the world. These groups are independent, non-profit-making organisations, the purpose of which is to provide an informal means of discussing and advancing hybrid technology. This is achieved by the organisation of meetings, the publication of a Newsletter and other activities as appropriate. Membership is open to all and there are no formal entry requirements.

All these societies run a programme of meetings throughout the year on subjects concerned with thick films, and interested readers are advised to contact the following Chairmen for details of meetings in their own areas:

#### 1. Benelux

Mr. G. K. Steenvoorden  
Technische Hogeschool Delft  
Lorentzweg 1  
NL.2628 C. J. DELFT  
Nederland

#### 2. France

Dr B. Dreyfus-Alain  
President de I.F.M.H.  
114 Rue de Danniette  
91190 GIF SUR YVETTE, France

#### 3. Germany

Herr W. Funk  
Philips Forschungslaboratorium GmbH  
2 HAMBURG 54  
Postfach 540840  
Deutschland

#### 4. Italy

Dr D. Roggia  
Telettra  
Via Trento 30  
20059 VIMERCATE  
Italy

#### 5. Japan

Dr A. Ikegami  
Hitachi Ltd.  
292 Yoshida-Cho  
Totsuka-ku  
YOKOHAMA  
Japan

#### 6. Nordic

Mr E. Järvinen  
Lohja Corporation  
Electronics Division  
Box 47  
SF-08101 Lohja 10  
Finland

#### 7. U.K.

Mr. A. Fairbairn  
Semi-Alloys Inc.  
Newbury,  
Berkshire,  
U.K.

#### 8. U.S.A. — all U.S. Chapters

I.S.H.M.  
P.O. Box 3255  
MONTGOMERY  
Alabama 36109, U.S.A.

In addition, the European Chapters are all linked together through the European Liaison Committee.  
Chairman:

Monsieur G. Kersuzan  
31 Résidence les Gros Chênes  
F-91370 VERRIÈRES LE BUISSON,  
France



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